

Title (en)

ELECTRICAL CONTACT OF THIN ENAMEL COVERED WIRES OF SECONDARY WINDINGS OF IGNITION COILS COMPRISING A CONTACT CROWN AND A CONTACT ELEMENT

Title (de)

ELEKTRISCHE KONTAKTIERUNG DÜNNER LACKDRÄHTE VON SEKUNDÄRWICKLUNGEN VON ZÜNDSPULEN MIT KONTAKTKRONE UND KONTAKTELEMENT

Title (fr)

MISE EN CONTACT ELECTRIQUE DE MINCES FILS LAQUES D'ENROULEMENTS SECONDAIRES DE BOBINES D'ALLUMAGE AU MOYEN D'UNE COURONNE DE CONTACT ET D'UN ELEMENT DE CONTACT

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Application

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Abstract (en)

[origin: WO2005071700A1] THE invention relates to an electrical connection system for producing an ignition coil. The aim of the invention is to replace conventional contacting methods for connecting thin enamel covered wires in ignition coils, such as for example thermal methods. For this purpose, one contact element (8) each is provided between the primary or secondary winding (5, 5') and the respective high-voltage or low-voltage output (H, N) for establishing contact. Said contact element can be slid with its one end over the primary or secondary winding (5, 5') and is fixed with its other end. The contact element (8) is configured as a spring-type element, has a slide face (13) and is fanned out on at least one side in the sliding direction (arrow 18) in a tulip-shaped manner to such an extent that, once mounted, the contact element (8) exerts a resilient pressure on the primary or secondary winding (5, 5') and breaks the insulation layer, thereby establishing electrical contact.

IPC 8 full level

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